

## III. Moldex3D Szeminárium - eCon Felhasználói Találkozó

### Programterv/Timetable

9 <sup>10</sup> – 9 <sup>30</sup>	<b>Regisztráció/Registration</b>
9 <sup>30</sup> – 10 <sup>00</sup>	Opening ceremony /eCon Engineering Kft/
10 <sup>00</sup> – 10 <sup>40</sup>	Technical presentation: Moldex3D R12 on Advanced Process Technology (GAIM, WAIM and ICM)/Coretech System Co. Ltd, Taiwan/
10 <sup>40</sup> – 11 <sup>00</sup>	<b>Coffee Break</b>
11 <sup>00</sup> – 11 <sup>40</sup>	Technical presentation-Live demo: Moldex3D Latest Technology on Fiber and Multiple Component Molding /Coretech System Co. Ltd, Taiwan/
11 <sup>40</sup> – 12 <sup>40</sup>	<b>Állófogadás/Lunch-time</b>
12 <sup>40</sup> – 13 <sup>20</sup>	Technical presentation-Live demo: Moldex3D-ANSYS coupling, FEA Interface /eCon Engineering Kft/

Regisztráció: <http://www.econengineering.com/konferencia>